

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claim 1 (previously presented): A water-permeable adhesive tape for processing semiconductor wafers and/or semiconductor related materials, comprising at least one base film which possesses perforations and has a cavity ratio of 3.0 to 90%; and an adhesive not having perforations applied on one surface of the base film.

Claim 2 (original): The water-permeable adhesive tape according to claim 1, wherein the base film comprises a synthetic resin or a non-woven fabric.

Claim 3 (original): The water-permeable adhesive tape according to claim 1 or 2, wherein the size of the perforations is from 0.001 to 3.0 mm².

Claim 4 (previously presented): The water-permeable adhesive tape according to any of claims 1 or 2, wherein the adhesive comprises a rubber-based or acrylic-based adhesive.

Claim 5 (previously presented): The water-permeable adhesive tape according to any of claims 1 or 2, wherein the adhesive is pressure-sensitive, light-sensitive and/or heat-sensitive.

Claim 6 (previously presented): The water-permeable adhesive tape according to any of claims 1 or 2, having an elongation of more than 10%.

Claim 7 (previously presented): The water-permeable adhesive tape according to any of claims 1 or 2, having a tensile strength of more than 0.1 N/20 mm.

AMENDMENT

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Claim 8 (previously presented): The water-permeable adhesive tape according to any of claims 1 or 2, having an adhesive strength of 0.15 to 10 N/20 mm.

Claim 9 (currently amended): ~~Use of the water-permeable adhesive tape according to claim 1 for~~ A method of processing semiconductor wafers and/or semiconductor-related materials, comprising a step of fixing a semiconductor wafer or semiconductor material with the water-permeable adhesive tape according to Claim 1.